

In re Application of:
Sun et al.

Serial No.: 10/616,097

Confirmation No.: 1645

Filed: July 8, 2003

For: Multiple-Step Electrodeposition Process for Direct Copper Plating on Barrier Materials

Group Art Unit: 1753

Examiner: Edna Wong

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Edna Wong, on the date shown below.

January 17, 2007
Date

John-Paul F. Cherry

Dear Sir:

RESPONSE TO OFFICE ACTION DATED OCTOBER 17, 2006

In response to the Office Action dated October 17, 2006, having a shortened statutory period for response set to expire on January 17, 2007, please enter this Response and reconsider the claims pending in the application for the reasons discussed below. Although the Applicant believes that no additional fees are due in connection with this Response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/JPC, for any fees, including extension of time fees or excess claim fees, required to make this Response timely and acceptable to the Office.

Amendments to the Claims begin on page 2 of this paper. **Remarks** begin on page 8 of this paper.